

XP-002121063

AN - 1980-44218C [25]

PR - JP19780133698 19781101

TI - Regeneration of soln. used for washing printed circuit boards - by filtering, removing copper ions with chelate type ion exchange resin and removing resulting sodium ions with cation exchange resin

IW - REGENERATE SOLUTION WASHING PRINT CIRCUIT BOARD FILTER REMOVE COPPER

ION CHELATE TYPE ION EXCHANGE RESIN REMOVE RESULT SODIUM ION CATION

EXCHANGE RESIN

PA - (HITA ) HITACHI LTD

PN - JP55062794 A 19800512 DW198025 000pp

- JP62006678B B 19870212 DW198710 000pp

IC - H05K3/26

✓ AB - J55062794 Recovered washing soln contg a large amt of Cu ions is filtered. Cu ions in the filtered soln are ion-exchanged using a chelate type ion exchange resin. The resulting Na ions are ion-exchanged using a cation exchange resin. The treated soln is reused as a washing soln for a printed circuit substrate.

- Typically a waste washing soln (hydrochloric acid, malic acid, isopropyl alcohol, and polyacrylamide) contg 1500 mg/l Cu is passed successively through a polypropylene filter tower, a chelate type ion exchange tower and a cation exchange resin tower. The soln thus treated has a concn. of unwanted floating material of <5 mg/l and a Cu concn of <3 mg/l. The regenerated washing soln is collected and reused.

- Unwanted Cu ions are easily removed from the waste washing soln.